## IN THE CLAIMS

1 (Currently Amended). A method comprising:

forming a heat transfer fin of a laminate of a metallic and a non-metallic layer, said

metallic layer providing structural integrity to the laminated fin. two different materials; and permanently securing said fin to a heat conductive base.

Claim 2 (Canceled).

- 3 (Currently Amended). The method of claim 1 including <u>permanently</u> securing said <u>fin to a heat conductive laminate to the</u> base using crimping.
- 4 (Currently Amended). The method of claim 2 1 including adhesively bonding said metallic and non-metallic materials layers.
- 5 (Original). The method of claim 1 wherein forming a heat transfer fin includes forming a fin of a laminate of a metallic and a pyrolytic graphite material.
- 6 (Original). The method of claim 1 including forming the fin with an aspect ratio higher than 20:1.
- 7 (Original). The method of claim 5 including forming the fin with an aspect ratio of 60:1.
- 8 (Original). The method of claim 1 including securing heat transfer fin to an integrated circuit.
- 9 (Original). The method of claim 8 including securing said heat transfer fin to a microprocessor.

- 10 (Original). The method of claim 2 including forming the metallic and non-metallic material of equal thicknesses.
- 11 (Currently Amended). A heat sink comprising:

  a heat sink fin including two different materials metallic and non-metallic materials,
  said metallic material providing structural integrity to said fin; and
  a conductive base, said fin secured to said base.

Claim 12 (Canceled).

- 13 (Original). The heat sink of claim 11 wherein said fin is crimped to said base.
- 14 (Currently Amended). The heat sink of claim 42 11 wherein said metallic and non-metallic materials are adhesively bonded.
- 15 (Currently Amended). The heat sink of claim 12 11 wherein said non-metallic material is a pyrolytic graphite material.
  - 16 (Original). The heat sink of claim 11 wherein the fin aspect ratio is higher than 20:1.
  - 17 (Original). The heat sink of claim 16 wherein the fin aspect ratio is 60:1.
- 18 (Original). The heat sink of claim 11 wherein said base is secured to an integrated circuit.
- 19 (Original). The heat sink of claim 18 wherein said integrated circuit is a microprocessor.
- 20 (Original). The heat sink of claim 11, said fin including a first sheet of metallic material and a second sheet of non-metallic material, said sheets being laminated together.

- 21 (Original). The heat sink of claim 20 wherein said first and second sheets are of equal thicknesses.
  - 22 (Currently Amended). An integrated circuit comprising: an integrated circuit chip; and
- a heat sink secured to said chip, said heat sink including a heat transfer fin of a laminate of metallic and non-metallic material, said metallic material providing structural integrity to said fin.
- 23 (Currently Amended). The circuit of claim 22 wherein said <u>heat sink includes a conductive base, and said</u> fin is crimped to said base.
- 24 (Original). The circuit of claim 22 wherein said metallic and non-metallic materials are adhesively bonded.
- 25 (Original). The circuit of claim 22 wherein said non-metallic material is a pyrolytic graphite material.
  - 26 (Original). The circuit of claim 22 wherein the fin aspect ratio is higher than 20:1.
  - 27 (Original). The circuit of claim 26 wherein the fin aspect ratio is 60:1.
- 28 (Currently Amended). The circuit of claim 22 wherein said <u>heat sink includes a</u> base is secured to <u>said an</u> integrated circuit <u>chip</u>.
- 29 (Original). The circuit of claim 28 wherein said integrated circuit chip is a microprocessor.
- 30 (Original). The circuit of claim 22 wherein said metallic and non-metallic material are of equal thicknesses.